Features

- **Compatible with MCS-51™ Products**
- **4K Bytes of Factory Programmable QuickFlash™ Memory**
- **Fully Static Operation: 0 Hz to 20 MHz**
- **Three-Level Program Memory Lock**
- **128 x 8-Bit Internal RAM**
- **32 Programmable I/O Lines**
- **Two 16-Bit Timer/Counters**
- **Six Interrupt Sources**
- **Programmable Serial Channel**
- **Low Power Idle and Power Down Modes**

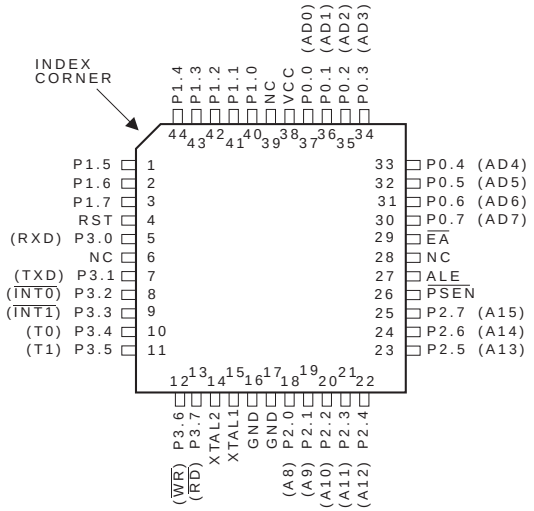
Description

The AT80F51 is a low-power, high-performance CMOS 8-bit microcomputer with 4K bytes of QuickFlash Memory. The device is manufactured using Atmel's high density nonvolatile memory technology and is compatible with the industry standard MCS-51™ instruction set and pinout. The on-chip QuickFlash allows custom codes to be quickly programmed in the factory. By combining a versatile 8-bit CPU with QuickFlash on a monolithic chip, the Atmel AT80F51 is a powerful microcomputer which provides a highly flexible and cost effective solution to many embedded control applications.

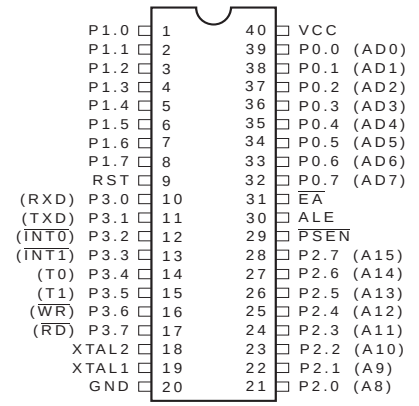
(continued)

Pin Configurations

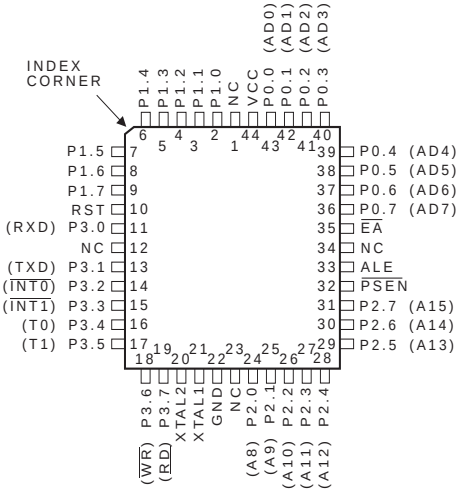
TQFP



PDIP



PLCC

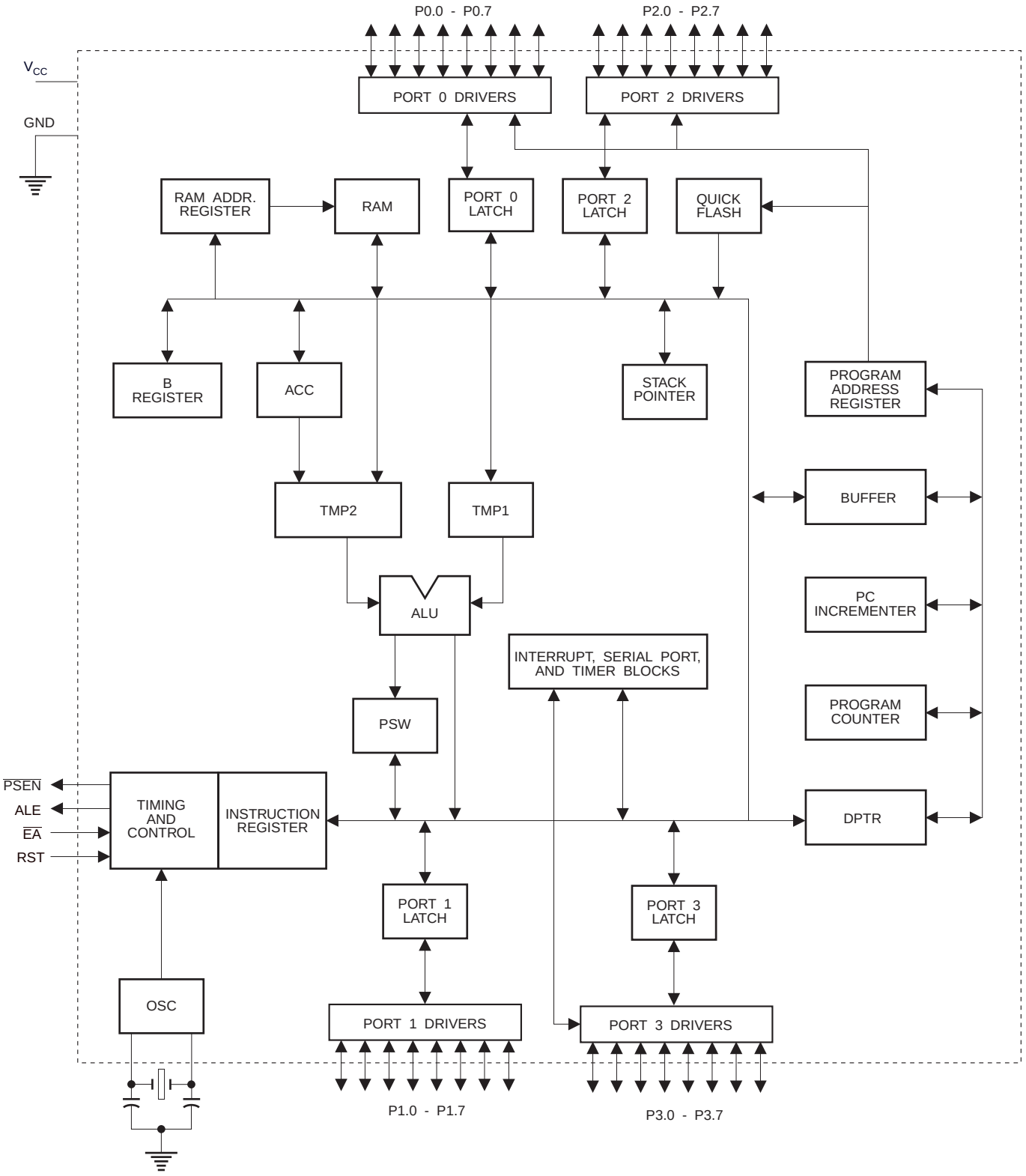


8-Bit Microcontroller with 4K Bytes QuickFlash™ Memory

AT80F51

0979A-A–12/97

Block Diagram



The AT80F51 provides the following standard features: 4K bytes of QuickFlash, 128 bytes of RAM, 32 I/O lines, two 16-bit timer/counters, a five vector two-level interrupt architecture, a full duplex serial port, on-chip oscillator and clock circuitry. In addition, the AT80F51 is designed with static logic for operation down to zero frequency and supports two software selectable power saving modes. The Idle Mode stops the CPU while allowing the RAM, timer/counters, serial port and interrupt system to continue functioning. The Power Down Mode saves the RAM contents but freezes the oscillator disabling all other chip functions until the next hardware reset.

Pin Description

V_{CC}
Supply voltage.

GND
Ground.

Port 0
Port 0 is an 8-bit open drain bidirectional I/O port. As an output port each pin can sink eight TTL inputs. When 1s are written to port 0 pins, the pins can be used as high-impedance inputs.

Port 0 may also be configured to be the multiplexed low-order address/data bus during accesses to external program and data memory. In this mode P0 has internal pullups.

Port 0 also outputs the code bytes during program verification. External pullups are required during program verification.

Port 1
Port 1 is an 8-bit bidirectional I/O port with internal pullups. The Port 1 output buffers can sink/source four TTL inputs. When 1s are written to Port 1 pins they are pulled high by the internal pullups and can be used as inputs. As inputs, Port 1 pins that are externally being pulled low will source current (I_{IL}) because of the internal pullups.

Port 1 also receives the low-order address bytes during QuickFlash verification.

Port 2
Port 2 is an 8-bit bidirectional I/O port with internal pullups. The Port 2 output buffers can sink/source four TTL inputs. When 1s are written to Port 2 pins they are pulled high by the internal pullups and can be used as inputs. As inputs, Port 2 pins that are externally being pulled low will source current (I_{IL}) because of the internal pullups.

Port 2 emits the high-order address byte during fetches from external program memory and during accesses to external data memory that use 16-bit addresses (MOVX @ DPTR). In this application it uses strong internal pullups when emitting 1s. During accesses to external data memory that use 8-bit addresses (MOVX @ RI), Port 2 emits the contents of the P2 Special Function Register.

Port 2 also receives the high-order address bits and some control signals during QuickFlash verification.

Port 3
Port 3 is an 8-bit bidirectional I/O port with internal pullups. The Port 3 output buffers can sink/source four TTL inputs. When 1s are written to Port 3 pins they are pulled high by the internal pullups and can be used as inputs. As inputs, Port 3 pins that are externally being pulled low will source current (I_{IL}) because of the pullups.

Port 3 also serves the functions of various special features of the AT80F51 as listed below:

Port Pin	Alternate Functions
P3.0	RXD (serial input port)
P3.1	TXD (serial output port)
P3.2	$\overline{\text{INT0}}$ (external interrupt 0)
P3.3	$\overline{\text{INT1}}$ (external interrupt 1)
P3.4	T0 (timer 0 external input)
P3.5	T1 (timer 1 external input)
P3.6	$\overline{\text{WR}}$ (external data memory write strobe)
P3.7	$\overline{\text{RD}}$ (external data memory read strobe)

Port 3 also receives some control signals for QuickFlash verification.

RST
Reset input. A high on this pin for two machine cycles while the oscillator is running resets the device.

ALE
Address Latch Enable output pulse for latching the low byte of the address during accesses to external memory.

In normal operation ALE is emitted at a constant rate of 1/6 the oscillator frequency, and may be used for external timing or clocking purposes. Note, however, that one ALE pulse is skipped during each access to external Data Memory.

If desired, ALE operation can be disabled by setting bit 0 of SFR location 8EH. With the bit set, ALE is active only during a MOVX or MOVC instruction. Otherwise, the pin is weakly pulled high. Setting the ALE-disable bit has no effect if the microcontroller is in external execution mode.

$\overline{\text{PSEN}}$
Program Store Enable is the read strobe to external program memory.

When the AT80F51 is executing code from external program memory, $\overline{\text{PSEN}}$ is activated twice each machine

cycle, except that two $\overline{PSEN}$ activations are skipped during each access to external data memory.

$\overline{EA}$

External Access Enable. $\overline{EA}$ must be strapped to GND in order to enable the device to fetch code from external program memory locations starting at 0000H up to FFFFH. Note, however, that if lock bit 1 is programmed, $\overline{EA}$ will be internally latched on reset.

$\overline{EA}$ should be strapped to V_{CC} for internal program executions.

XTAL1

Input to the inverting oscillator amplifier and input to the internal clock operating circuit.

XTAL2

Output from the inverting oscillator amplifier.

Oscillator Characteristics

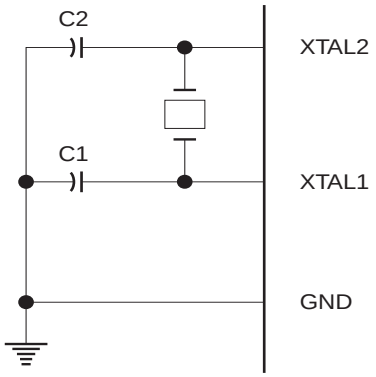
XTAL1 and XTAL2 are the input and output, respectively, of an inverting amplifier which can be configured for use as an on-chip oscillator, as shown in Figure 1. Either a quartz crystal or ceramic resonator may be used. To drive the device from an external clock source, XTAL2 should be left unconnected while XTAL1 is driven as shown in Figure 2. There are no requirements on the duty cycle of the external clock signal, since the input to the internal clocking circuitry is through a divide-by-two flip-flop, but minimum and maximum voltage high and low time specifications must be observed.

Idle Mode

In idle mode, the CPU puts itself to sleep while all the on-chip peripherals remain active. The mode is invoked by software. The content of the on-chip RAM and all the special functions registers remain unchanged during this mode. The idle mode can be terminated by any enabled interrupt or by a hardware reset.

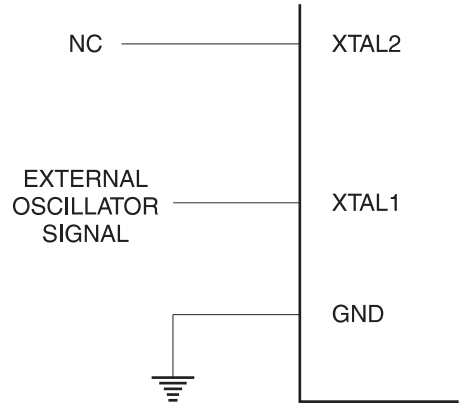
It should be noted that when idle is terminated by a hard ware reset, the device normally resumes program execution, from where it left off, up to two machine cycles before the internal reset algorithm takes control. On-chip hardware inhibits access to internal RAM in this event, but access to the port pins is not inhibited. To eliminate the possibility of an unexpected write to a port pin when Idle is terminated by reset, the instruction following the one that invokes Idle should not be one that writes to a port pin or to external memory.

Figure 1. Oscillator Connections



Note: C1, C2 = 30 pF ± 10 pF for Crystals
= 40 pF ± 10 pF for Ceramic Resonators

Figure 2. External Clock Drive Configuration



Power Down Mode

In the power down mode the oscillator is stopped, and the instruction that invokes power down is the last instruction executed. The on-chip RAM and Special Function Registers retain their values until the power down mode is termi-

Status of External Pins During Idle and Power Down Modes

Mode	Program Memory	ALE	$\overline{PSEN}$	PORT0	PORT1	PORT2	PORT3
Idle	Internal	1	1	Data	Data	Data	Data
Idle	External	1	1	Float	Data	Address	Data
Power Down	Internal	0	0	Data	Data	Data	Data
Power Down	External	0	0	Float	Data	Data	Data

nated. The only exit from power down is a hardware reset. Reset redefines the SFRs but does not change the on-chip RAM. The reset should not be activated before V_{CC} is restored to its normal operating level and must be held active long enough to allow the oscillator to restart and stabilize.

Program Memory Lock Bits

On the chip are three lock bits which can be left unprogrammed (U) or can be programmed (P) to obtain the additional features listed in the table below:

When lock bit 1 is programmed, the logic level at the $\overline{EA}$ pin is sampled and latched during reset. If the device is powered up without a reset, the latch initializes to a random value, and holds that value until reset is activated. It is necessary that the latched value of $\overline{EA}$ be in agreement with the current logic level at that pin in order for the device to function properly.

Lock Bit Protection Modes

Program Lock Bits				Protection Type
	LB1	LB2	LB3	
1	U	U	U	No program lock features.
2	P	U	U	MOVC instructions executed from external program memory are disabled from fetching code bytes from internal memory, $\overline{EA}$ is sampled and latched on reset, and further programming of the QuickFlash is disabled.
3	P	P	U	Same as mode 2, also verify is disabled.
4	P	P	P	Same as mode 3, also external execution is disabled.

Programming/Verifying the QuickFlash

The AT80F51 can only be programmed by Atmel. Customer codes should be submitted in **duplicate** on a floppy disk or uploaded to Atmel's bulletin board or Web site. The code should be in the Intel Hex format. The desired states of the Lock Bits should be specified. Once programmed, the code memory and Lock Bits cannot be erased or reprogrammed.

Please consult the factory or Atmel's representatives for details on submitting custom codes.

Program Verify: If lock bits LB1 and LB2 have not been programmed, the programmed code data can be read back via the address and data lines for verification. The lock bits cannot be verified directly. Verification of the lock bits is achieved by observing that their features are enabled.

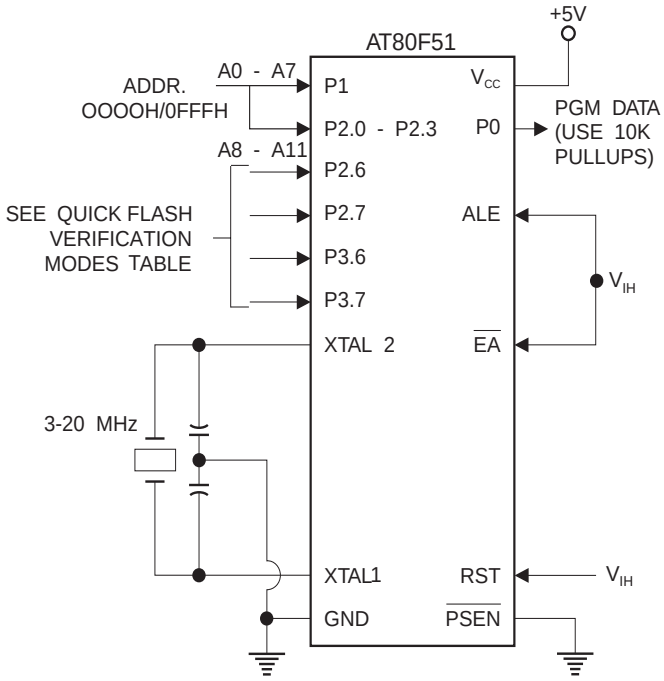
Reading the Signature Bytes: The signature bytes are read by the same procedure as a normal verification of locations 030H, 031H, and 032H, except that P3.6 and P3.7 must be pulled to a logic low. The values returned are as follows.

(030H) = 1EH indicates manufactured by Atmel
(031H) = 80H indicates QuickFlash
(032H) = 01H indicates AT80F51

QuickFlash Verification Modes

Mode	RST	$\overline{PSEN}$	ALE	$\overline{EA}$	P2.6	P2.7	P3.6	P3.7
Read Code Data	H	L	H	H	L	L	H	H
Read Signature Byte	H	L	H	H	L	L	L	L

Figure 3. Verifying the QuickFlash

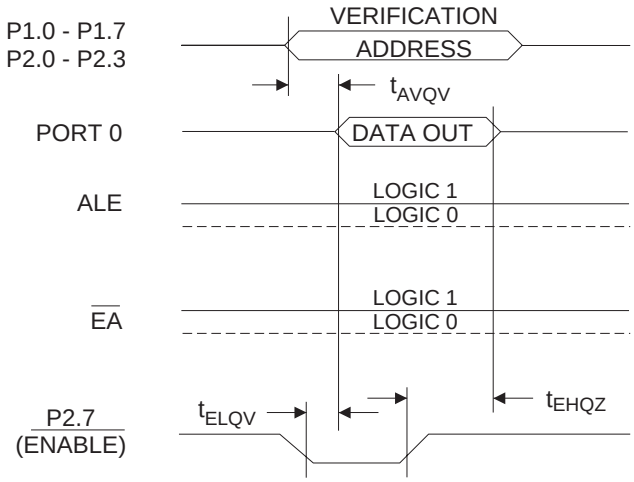


QuickFlash Verification Characteristics

T_A = 0°C to 70°C, V_{CC} = 5.0 ± 10%

Symbol	Parameter	Min	Max	Units
$1/t_{CLCL}$	Oscillator Frequency	3	20	MHz
t_{AVQV}	Address to Data Valid		$48t_{CLCL}$	
t_{ELQV}	$\overline{\text{ENABLE}}$ Low to Data Valid		$48t_{CLCL}$	
t_{EHQZ}	Data Float After $\overline{\text{ENABLE}}$	0	$48t_{CLCL}$	

QuickFlash Verification Waveforms



Absolute Maximum Ratings*

Operating Temperature	-55°C to +125°C
Storage Temperature	-65°C to +150°C
Voltage on Any Pin with Respect to Ground	-1.0V to +7.0V
Maximum Operating Voltage	6.6V
DC Output Current	15.0 mA

*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

DC Characteristics

T_A = -40°C to 85°C, V_{CC} = 5.0V ± 20% (unless otherwise noted)

Symbol	Parameter	Condition	Min	Max	Units
V_{IL}	Input Low Voltage	(Except $\overline{EA}$)	-0.5	0.2 V_{CC} - 0.1	V
V_{IL1}	Input Low Voltage ($\overline{EA}$)		-0.5	0.2 V_{CC} - 0.3	V
V_{IH}	Input High Voltage	(Except XTAL1, RST)	0.2 V_{CC} + 0.9	V_{CC} + 0.5	V
V_{IH1}	Input High Voltage	(XTAL1, RST)	0.7 V_{CC}	V_{CC} + 0.5	V
V_{OL}	Output Low Voltage(1) (Ports 1,2,3)	I_{OL} = 1.6 mA		0.45	V
V_{OL1}	Output Low Voltage(1) (Port 0, ALE, $\overline{PSEN}$)	I_{OL} = 3.2 mA		0.45	V
V_{OH}	Output High Voltage (Ports 1,2,3, ALE, $\overline{PSEN}$)	I_{OH} = -60 µA, V_{CC} = 5V ± 10%	2.4		V
		I_{OH} = -25 µA	0.75 V_{CC}		V
		I_{OH} = -10 µA	0.9 V_{CC}		V
V_{OH1}	Output High Voltage (Port 0 in External Bus Mode)	I_{OH} = -800 µA, V_{CC} = 5V ± 10%	2.4		V
		I_{OH} = -300 µA	0.75 V_{CC}		V
		I_{OH} = -80 µA	0.9 V_{CC}		V
I_{IL}	Logical 0 Input Current (Ports 1,2,3)	V_{IN} = 0.45V		-50	µA
I_{TL}	Logical 1 to 0 Transition Current (Ports 1,2,3)	V_{IN} = 2V, VCC = 5V ± 10%		-650	µA
I_{LI}	Input Leakage Current (Port 0, $\overline{EA}$)	0.45 < V_{IN} < V_{CC}		±10	µA
RRST	Reset Pulldown Resistor		50	300	KΩ
C_{IO}	Pin Capacitance	Test Freq. = 1 MHz, T_A = 25°C		10	pF
I_{CC}	Power Supply Current	Active Mode, 12 MHz		20	mA
		Idle Mode, 12 MHz		5	mA
	Power Down Mode(2)	V_{CC} = 6V		100	µA
		V_{CC} = 3V		40	µA

Notes: 1. Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows:
Maximum I_{OL} per port pin: 10 mA
Maximum I_{OL} per 8-bit port: Port 0: 26 mA
Ports 1, 2, 3: 15 mA
Maximum total I_{OL} for all output pins: 71 mA
If I_{OL} exceeds the test condition, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.

2. Minimum V_{CC} for Power Down is 2V.

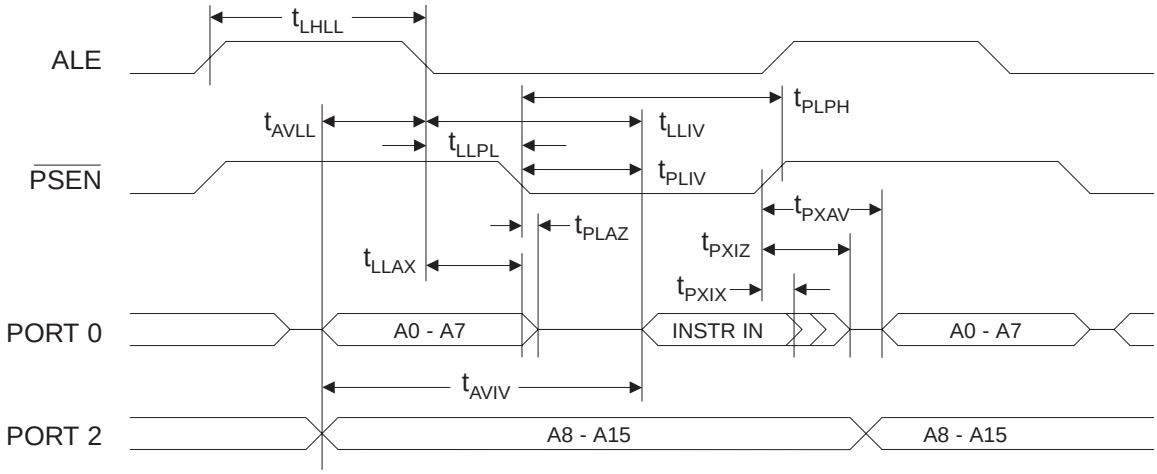
AC Characteristics

(Under Operating Conditions; Load Capacitance for Port 0, ALE, and $\overline{PSEN}$ = 100 pF; Load Capacitance for all other outputs = 80 pF)

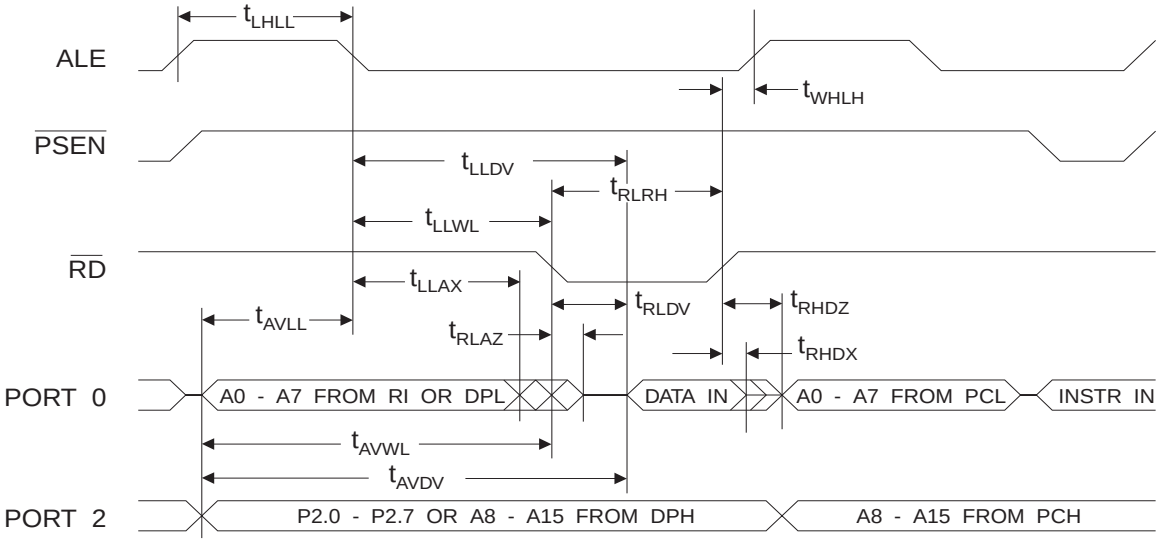
External Program and Data Memory Characteristics

Symbol	Parameter	12 MHz Oscillator		Variable Oscillator		Units
		Min	Max	Min	Max	
$1/t_{CLCL}$	Oscillator Frequency			0	20	MHz
t_{LHLL}	ALE Pulse Width	127		$2t_{CLCL}$-40		ns
t_{AVLL}	Address Valid to ALE Low	43		t_{CLCL}-13		ns
t_{LLAX}	Address Hold After ALE Low	48		t_{CLCL}-20		ns
t_{LLIV}	ALE Low to Valid Instruction In		233		$4t_{CLCL}$-65	ns
t_{LLPL}	ALE Low to $\overline{PSEN}$ Low	43		t_{CLCL}-13		ns
t_{PLPH}	$\overline{PSEN}$ Pulse Width	205		$3t_{CLCL}$-20		ns
t_{PLIV}	$\overline{PSEN}$ Low to Valid Instruction In		145		$3t_{CLCL}$-45	ns
t_{PXIX}	Input Instruction Hold After $\overline{PSEN}$	0		0		ns
t_{PXIZ}	Input Instruction Float After $\overline{PSEN}$		59		t_{CLCL}-10	ns
t_{PXAV}	$\overline{PSEN}$ to Address Valid	75		t_{CLCL}-8		ns
t_{AVIV}	Address to Valid Instruction In		312		$5t_{CLCL}$-55	ns
t_{PLAZ}	$\overline{PSEN}$ Low to Address Float		10		10	ns
t_{RLRH}	$\overline{RD}$ Pulse Width	400		$6t_{CLCL}$-100		ns
t_{WLWH}	$\overline{WR}$ Pulse Width	400		$6t_{CLCL}$-100		ns
t_{RLDV}	$\overline{RD}$ Low to Valid Data In		252		$5t_{CLCL}$-90	ns
t_{RHDX}	Data Hold After $\overline{RD}$	0		0		ns
t_{RHDZ}	Data Float After $\overline{RD}$		97		$2t_{CLCL}$-28	ns
t_{LLDV}	ALE Low to Valid Data In		517		$8t_{CLCL}$-150	ns
t_{AVDV}	Address to Valid Data In		585		$9t_{CLCL}$-165	ns
t_{LLWL}	ALE Low to $\overline{RD}$ or $\overline{WR}$ Low	200	300	$3t_{CLCL}$-50	$3t_{CLCL}$+50	ns
t_{AVWL}	Address to $\overline{RD}$ or $\overline{WR}$ Low	203		$4t_{CLCL}$-75		ns
t_{QVWX}	Data Valid to $\overline{WR}$ Transition	23		t_{CLCL}-20		ns
t_{QVWH}	Data Valid to $\overline{WR}$ High	433		$7t_{CLCL}$-120		ns
t_{WHQX}	Data Hold After $\overline{WR}$	33		t_{CLCL}-20		ns
t_{RLAZ}	$\overline{RD}$ Low to Address Float		0		0	ns
t_{WHLH}	$\overline{RD}$ or $\overline{WR}$ High to ALE High	43	123	t_{CLCL}-20	t_{CLCL}+25	ns

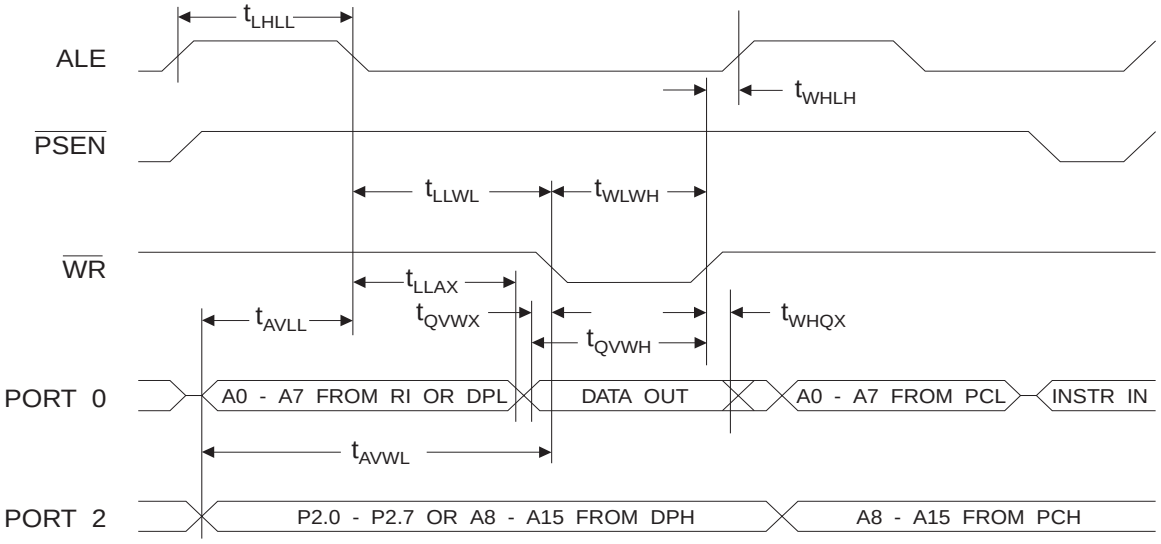
External Program Memory Read Cycle



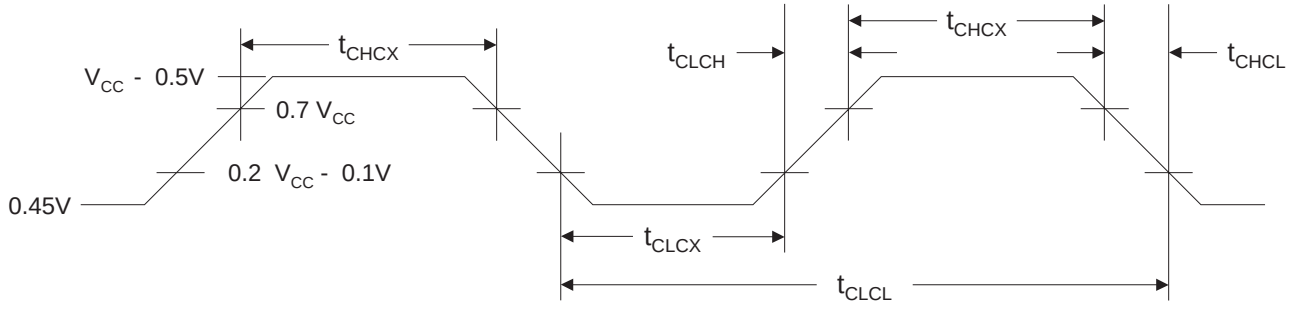
External Data Memory Read Cycle



External Data Memory Write Cycle



External Clock Drive Waveforms



External Clock Drive

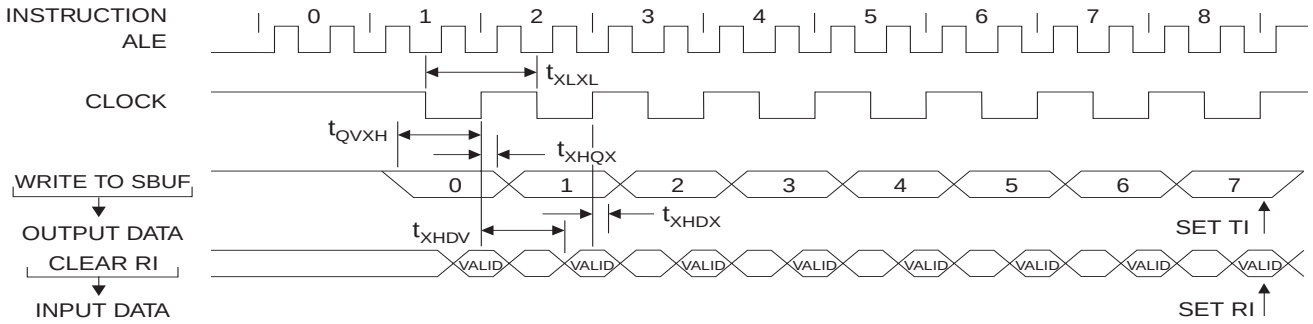
Symbol	Parameter	Min	Max	Units
$1/t_{CLCL}$	Oscillator Frequency	0	20	MHz
t_{CLCL}	Clock Period	41.6		ns
t_{CHCX}	High Time	15		ns
t_{CLCX}	Low Time	15		ns
t_{CLCH}	Rise Time		20	ns
t_{CHCL}	Fall Time		20	ns

Serial Port Timing: Shift Register Mode Test Conditions

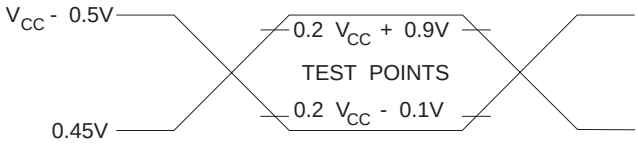
(V_{CC} = 5.0 V ± 20%; Load Capacitance = 80 pF)

Symbol	Parameter	12 MHz Osc		Variable Oscillator		Units
		Min	Max	Min	Max	
t_{XLXL}	Serial Port Clock Cycle Time	1.0		$12t_{CLCL}$		µs
t_{QVXH}	Output Data Setup to Clock Rising Edge	700		$10t_{CLCL}$-133		ns
t_{XHQX}	Output Data Hold After Clock Rising Edge	50		$2t_{CLCL}$-117		ns
t_{XHDX}	Input Data Hold After Clock Rising Edge	0		0		ns
t_{XHDV}	Clock Rising Edge to Input Data Valid		700		$10t_{CLCL}$-133	ns

Shift Register Mode Timing Waveforms

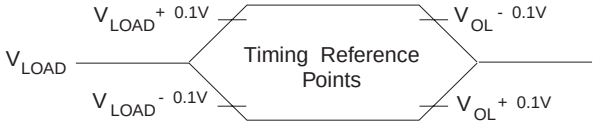


AC Testing Input/Output Waveforms(1)



Note: 1. AC Inputs during testing are driven at V_{CC} - 0.5V for a logic 1 and 0.45V for a logic 0. Timing measurements are made at V_{IH} min. for a logic 1 and V_{IL} max. for a logic 0.

Float Waveforms(1)



Note: 1. For timing purposes, a port pin is no longer floating when a 100 mV change from load voltage occurs. A port pin begins to float when 100 mV change from the loaded V_{OH}/V_{OL} level occurs.

Ordering Information

Speed (MHz)	Power Supply	Ordering Code	Package	Operation Range
12	5V ± 20%	AT80F51-12AC AT80F51-12JC AT80F51-12PC	44A 44J 40P6	Commercial (0°C to 70°C)
		AT80F51-12AI AT80F51-12JI AT80F51-12PI	44A 44J 40P6	Industrial (-40°C to 85°C)
16	5V ± 20%	AT80F51-16AC AT80F51-16JC AT80F51-16PC	44A 44J 40P6	Commercial (0°C to 70°C)
		AT80F51-16AI AT80F51-16JI AT80F51-16PI	44A 44J 40P6	Industrial (-40°C to 85°C)
20	5V ± 20%	AT80F51-20AC AT80F51-20JC AT80F51-20PC	44A 44J 40P6	Commercial (0°C to 70°C)
		AT80F51-20AI AT80F51-20JI AT80F51-20PI	44A 44J 40P6	Industrial (-40°C to 85°C)

Package Type	
44A	44-Lead, Thin Plastic Gull Wing Quad Flatpack (TQFP)
44J	44-Lead, Plastic J-Leaded Chip Carrier (PLCC)
40P6	40-Lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)